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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/943,487	08/30/2001	Yakov Epshteyn	SFI 718D1	9680
27782	7590	11/05/2003	EXAMINER	
SPEEDFAM-IPEC CORPORATION 305 NORTH 54TH STREET CHANDLER, AZ 85226			TRAN, BINH X	
			ART UNIT	PAPER NUMBER
			1765	

DATE MAILED: 11/05/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	Application No. 09/943,487	Applicant(s) EPSHTEYN ET AL.	
	Examiner Binh X Tran	Art Unit 1765	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☒ Responsive to communication(s) filed on 01 October 2003.
- 2a) ☐ This action is FINAL.                      2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 8-21 and 23-29 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☒ Claim(s) 8-21 and 23-29 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.  
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on \_\_\_\_\_ is: a) ☐ approved b) ☐ disapproved by the Examiner.  
If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

**Priority under 35 U.S.C. §§ 119 and 120**

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  
a) ☐ All b) ☐ Some \* c) ☐ None of:  
1. ☐ Certified copies of the priority documents have been received.  
2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.  
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  
\* See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).  
a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

**Attachment(s)**

- |  |   |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)                  | 4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s). _____  |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)         | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____ | 6) <input type="checkbox"/> Other:  |

## DETAILED ACTION

### ***Continued Examination Under 37 CFR 1.114***

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on 10-1-2003 has been entered.

### ***Claim Rejections - 35 USC § 112***

2. The following is a quotation of the second paragraph of 35 U.S.C. 112:

*The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.*

3. Claim 26 is rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

4. Claim 26 contains the trademark/trade name "Politex Supreme". Where a trademark or trade name is used in a claim as a limitation to identify or describe a particular material or product, the claim does not comply with the requirements of 35 U.S.C. 112, second paragraph. See *Ex parte Simpson*, 218 USPQ 1020 (Bd. App. 1982). The claim scope is uncertain since the trademark or trade name cannot be used properly to identify any particular material or product. A trademark or trade name is used to identify a source of goods, and not the goods themselves. Thus, a trademark or

Art Unit: 1765

trade name does not identify or describe the goods associated with the trademark or trade name. In the present case, the trademark/trade name is used to identify/describe the material for the pad and, accordingly, the identification/description is indefinite.

***Claim Rejections - 35 USC § 103***

5. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

6. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

7. Claims 8-17, 23-25, 27-29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Li et al. (US 6,436,302) in view of Swedek et al. (US 6,190,234).

removing a material (13) overlying a barrier layer (12) from the surface of the semiconductor wafer at a chemical mechanical polishing (CMP) station with a chemical mechanical polishing pad (Fig 1-2);

removing the barrier layer (12) from the semiconductor surface of the semiconductor wafer at a buff station using a buff pad and first barrier slurry (col. 7 lines 31-35, Fig 3; Note: the examiner interprets that barrier layer material (12) removed during the buffing step is mixed with the input slurry to provide a "barrier layer slurry").

Li does not explicitly disclose using abrasive slurry on a chemical mechanical polishing process. However, Li clearly discloses the step of performing a CMP process to remove material (13). In a CMP process, Swedek discloses using abrasive slurry particles (col. 5 lines 5-12). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Li in view of Swedek by using abrasive slurry because it will enhance the polishing process. Further the use of abrasive slurry is well known in the CMP process.

Respect to claim 9, Li discloses the step of buffing the wafer surface after barrier layer removal (col. 7 lines 36-45). Respect to claim 10, Li discloses a set of buff station parameters are different for the barrier layer removal step than for the buffing step. Respect to claim 11, Li discloses a different slurry composition is used for the barrier layer removal process (i.e. first buffering) than for the wafer buffing step (i.e. second and/or third buffing step) (See col. 6-8).

Respect to claims 12-13, Li fails to disclose the step of detecting material layer and/or barrier layer is substantially removed from the wafer. Swedek discloses the endpoint detecting step to determine whether any material is substantially removed from the wafer. It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Li in view of Swedek by detecting when the material or the barrier

Art Unit: 1765

layer is substantially removed from the wafer because it help us to determine when to stop the removal step.

Respect to claims 14-17, Swedek discloses the endpoint detection system using optical detection system includes infrared or laser detection system (col. 6 lines 1-10 and col.14 lines 60-67). Respect to claims 23-24, Li discloses the layer (13) comprises copper and the barrier layer (12) comprises TaN (col. 6 lines 42-47). Respect to claim 25, the cited prior arts teaches supplying the first polishing slurry to the primary or first polishing station and supply a different slurry to the buff station. Respect to claims 27-28, Li discloses removing the barrier layer (12) using slurry comprises abrasive suspension or using slurry comprises acidic or basic solution (col. 5 lines 35-47).

Respect to claim 29, Li discloses the second buffing step comprises abrasive slurry and a solution that includes deionized water (col. 7, read on "diluted first barrier slurry").

8. Claim 18 is rejected under 35 U.S.C. 103(a) as being unpatentable over Li and Swedek as applied to claim 8 above, and further in view of Easter (US 6,254,454).

Swedek fails to disclose the endpoint detection system is comprises of motor current detection system. However, Swedek clearly discloses the use of the endpoint detection system. In a semiconductor method, Easter discloses the use of the motor current detection system. It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Li and Swedek in view of Easter by using the motor current detection system because equivalent and substitution of one for the other would produce an expected result.

9. Claims 19-21 is rejected under 35 U.S.C. 103(a) as being unpatentable over Li and Swedek as applied to claim 8 above, and further in view of Mok (US 6,343,975).

Respect to claim 19, Li and Swedek fail to disclose the step of conditioning the buff station pads. Mok discloses the step of conditioning the buffing station pad (col. 3 lines 58-67). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Li and Swedek in view of Mok by conditioning the buffing station pad because it will maintain the pad so that it will effectively remove material from the substrate.

Respect to claim 20, Mok discloses the conditioning step is accomplished by pressing the lower pad against the upper pad and rotating each pad at different velocity (col. 3). Respect to claim 21, Mok discloses the conditioning is performed between each wafer being process.

10. Claim 26 is rejected under 35 U.S.C. 103(a) as being unpatentable over Li and Swedek as applied to claim 8 above, and further in view of Wang et al. (US 6,395,635).

Li and Swedek fail to disclose using a Politex Supreme buff pad to remove the barrier layer. However, Li clearly disclose using a buff pad to remove barrier layer. Wang discloses using a Politex Supreme pad to buff the layer (col. 4 lines 50-65). It would have been obvious to one having ordinary skill in the art, at the time of invention, to modify Li and Swedek by using Politex Supreme because this pad material capable of remove micro-scratch.

***Response to Arguments***

Application/Control Number: 09/943,487  
Art Unit: 1765

Page 7

11. Applicant's arguments with respect to claims 8-21, 23-25 have been considered but are moot in view of the new ground(s) of rejection.

***Conclusion***

12. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Binh X Tran whose telephone number is (703) 308-1867. The examiner can normally be reached on Monday-Thursday and every other Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine G Norton can be reached on (703) 305-2667. The fax phone number for the organization where this application or proceeding is assigned is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0661.

Binh X. Tran



ROBERT KUNEMUND  
PRIMARY EXAMINER